Docket No.:			
•	DECLARATION AN	D POWER OF AT	TORNEY
As a below named inventor	;, I hereby declare that:		
My residence, post office a	nd citizenship are as stated below ne	ext to my name,	
I believe I am the original, are listed below) of the sub	first and sole inventor (if only one pect matter claimed and for which a	name is listed below) or an ori patent is sought on the invent	ginal, first and joint inventor (if plural names ion entitled
PLATING MET	HOD FOR PCB		the specification of which
[X] is attached hereto and was	. ,		as Application Serial No.
	amended on		
I hereby state that I have re any amendment referred to		s of the above identified spec	ification, including the claims, as amended by
I acknowledge the duty to Federal Regulations, Sectio		n to me to be material to pate	ntability in accordance with Title 37, Code of
certificate, or 365(a) of any listed below and have also	PCT international application which	th designated at least one cour x, any foreign application for	oreign application(s) for patent or inventor's entry other than the United States of America, patent or inventor's certificate, or of any PCT is claimed.
Prior Foreign Application Number	n(s): <u>Country</u>		Foreign Filing Date Month/Day/Year
55977/2002	Korea		. 09/14/02
I hereby claim the benefit t	ander 35 U.S.C. 119(e) of any United	d States provisional application	n(s) listed below.
Application Number(s):	Filin	ng Date (Month/Day/Year)	
designating the United Sta disclosed in the prior Unit acknowledge the duty to	tes of America, listed below and, in ted States or PCT international app	sofar as the subject matter o lication in the manner provid erial to patentability as defin	365(c) of any PCT international application is each of the claims of this application is not ed by the first paragraph of 35 U.S.C. 112, I ed in 37 CFR 1.56 which became available ate of this application.
Prior U. S. Application or PCT Parent Number	<u>Filing Date (N</u>	Ionth/Day/Year)	Parent Patent
Number (if applicable)			•

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false

statements may jeopardize the validity of the application or any patent issued thereon.

Gunpo, Gyonggi-Do, Korea

I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vazquez, Registration No. 38,647; Michael J. Cornelison, Registration No. 40,395; and Stuart I. Smith, Registration No. 42,159; and Carol L. Druzbick, Registration No. 40,287, all of

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with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and all future correspondence should be addressed to them. Full name of sole or first inventor: Yu- Seock YANG Date: 17.14.2003 Inventor's signature: Residence: Seoul, Korea Citizenship: Republic of Korea Post Office Address: 598-164, Shinlim 12-Dong, Gwanak-Gu, Seoul, Korea Full name of joint inventor(s): Sung-Gue LEE Sung Gue Lee Inventor's signature: Residence: Hwaseong, Gyeonggi-Do, Korea Citizenship: Republic of Korea Post Office Address: Sinyoungtong Hyundai Apt. 301-1201, Banweol-Li, Taean-Eup, Hwaseong, Gyeonggi-Do, Korea Full name of joint inventor(s): Yong-Soon JANG Inventor's signature: Residence: Osan, Gyeonggi-Do, Korea Citizenship: Republic of Korea Post Office Address: Unam Chonggu Apt. 103-1606, 814-2, Won-Dong, Osan, Gyeonggi-Do, Korea Full name of joint inventor(s): Hyung-Kun KIM Inventor's signature: Residence: Gunpo, Gyonggi-Do, Korea Citizenship: Republic of Korea Post Office Address: LG Baekhap Apt. 1128-201, Sanbon-2 Dong,